

SOT655-1

plastic thin fine-pitch ball grid array package; 228 balls; body
12 x 12 x 0.8 mm

8 February 2016

Package information

1. Package summary

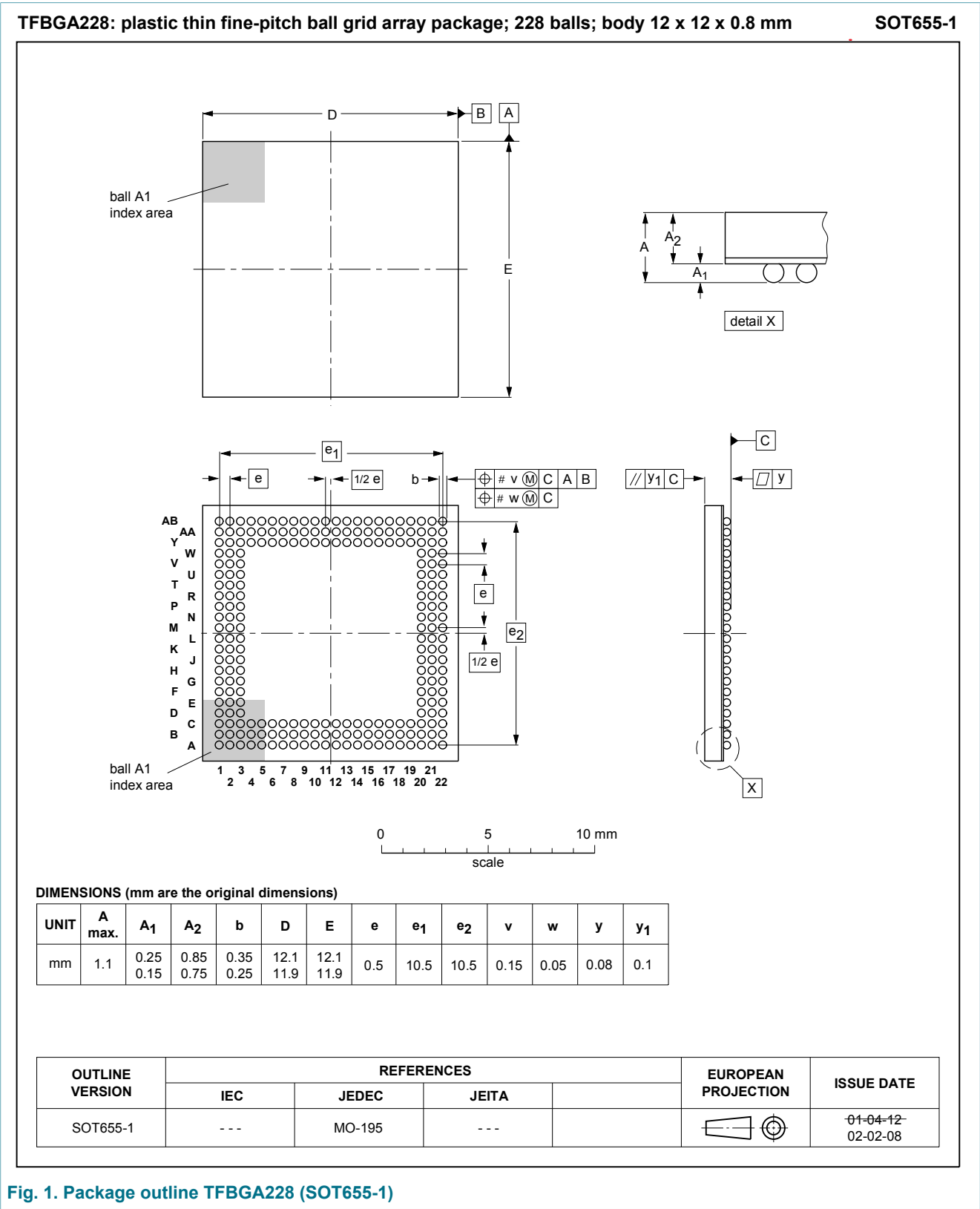
Terminal position code	B (bottom)
Package type descriptive code	TFBGA228
Package type industry code	TFBGA228
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	8-2-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		[tbd]	-	1.1	1.1	mm
A ₂	package height		0.75	-	0.8	0.85	mm
n ₂	actual quantity of termination		-	-	228	-	



2. Package outline



3. Soldering

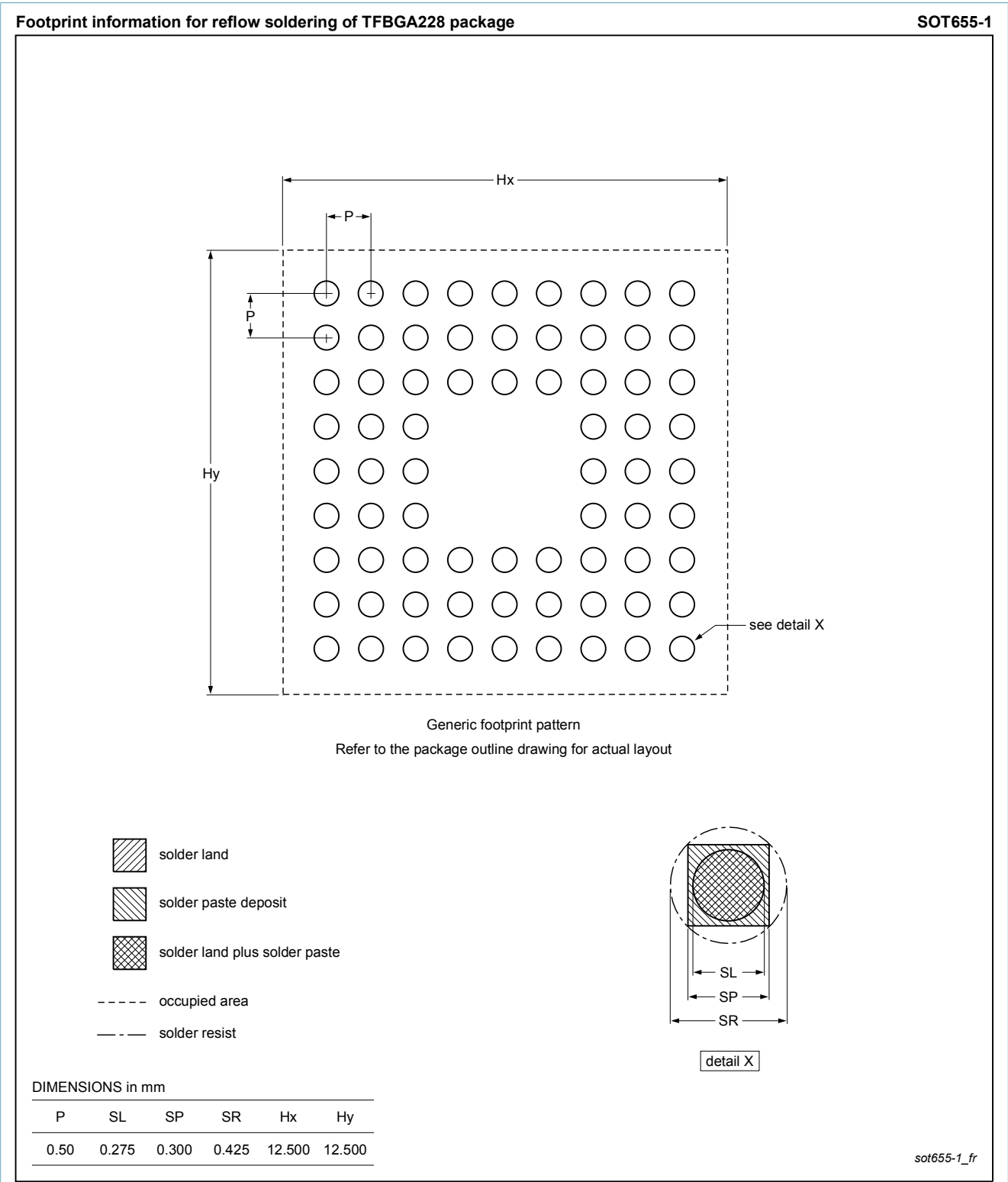


Fig. 2. Reflow soldering footprint for TFBGA228 (SOT655-1)

4. Legal information

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